

## FEATURES

- Member of Texas Instruments Widebus™ Family
- OEC™ Circuitry Improves Signal Integrity and Reduces Electromagnetic Interference
- D-Type Flip-Flops With Qualified Storage Enable
- Translates Between GTL/GTL+ Signal Levels and LVTTTL Logic Levels
- Supports Mixed-Mode (3.3 V and 5 V) Signal Operation on A-Port and Control Inputs
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors on A Port
- Distributed  $V_{CC}$  and GND Pins Minimize High-Speed Noise
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

The SN74GTL16622A is an 18-bit registered bus transceiver that provides LVTTTL-to-GTL/GTL+ and GTL/GTL+-to-LVTTTL signal-level translation. This device is partitioned as two separate 9-bit transceivers with individual clock-enable controls and contains D-type flip-flops for temporary storage of data flowing in either direction. This device provides an interface between cards operating at LVTTTL logic levels and a backplane operating at GTL/GTL+ signal levels. Higher-speed operation is a direct result of the reduced output swing (<1 V), reduced input threshold levels, and OEC™ circuitry.

The user has the flexibility of using this device at either GTL ( $V_{TT} = 1.2$  V and  $V_{REF} = 0.8$  V) or the preferred higher noise margin GTL+ ( $V_{TT} = 1.5$  V and  $V_{REF} = 1$  V) signal levels. GTL+ is the Texas Instruments derivative of the Gunning Transceiver Logic (GTL) JEDEC standard JESD 8-3. The B port normally operates at GTL or GTL+ signal levels, while the A-port and control inputs are compatible with LVTTTL logic levels and are 5-V tolerant.  $V_{REF}$  is the reference input voltage for the B port.

Data flow in each direction is controlled by the output-enable ( $\overline{OEAB}$  and  $\overline{OEBA}$ ) and clock (CLKAB and CLKBA) inputs. The clock-enable (CEAB and CEBA) inputs control each 9-bit transceiver independently, which makes the device more versatile.

DGG PACKAGE  
(TOP VIEW)

$\overline{OEAB}$	1	64	CLKAB
1A1	2	63	$\overline{1CEAB}$
GND	3	62	$\overline{1CEBA}$
1A2	4	61	1B1
1A3	5	60	GND
GND	6	59	1B2
$V_{CC}$	7	58	1B3
1A4	8	57	$V_{CC}$
GND	9	56	1B4
1A5	10	55	1B5
1A6	11	54	1B6
GND	12	53	GND
1A7	13	52	1B7
1A8	14	51	1B8
GND	15	50	GND
1A9	16	49	1B9
2A1	17	48	2B1
GND	18	47	GND
2A2	19	46	2B2
2A3	20	45	2B3
GND	21	44	GND
2A4	22	43	2B4
2A5	23	42	2B5
GND	24	41	2B6
2A6	25	40	$V_{REF}$
$V_{CC}$	26	39	2B7
GND	27	38	2B8
2A7	28	37	GND
2A8	29	36	2B9
GND	30	35	$\overline{2CEBA}$
2A9	31	34	$\overline{2CEAB}$
$\overline{OEBA}$	32	33	CLKBA



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**DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

For A-to-B data flow, the device operates on the low-to-high transition of CLKAB if  $\overline{CEAB}$  is low. When  $\overline{OEAB}$  is low, the outputs are active. When  $\overline{OEAB}$  is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B, but uses  $\overline{OEBA}$ , CLKBA, and  $\overline{CEBA}$ .

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Active bus-hold circuitry holds unused or undriven LVTTTL inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

**ORDERING INFORMATION**

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74GTL16622ADGGR	GTL16622A

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

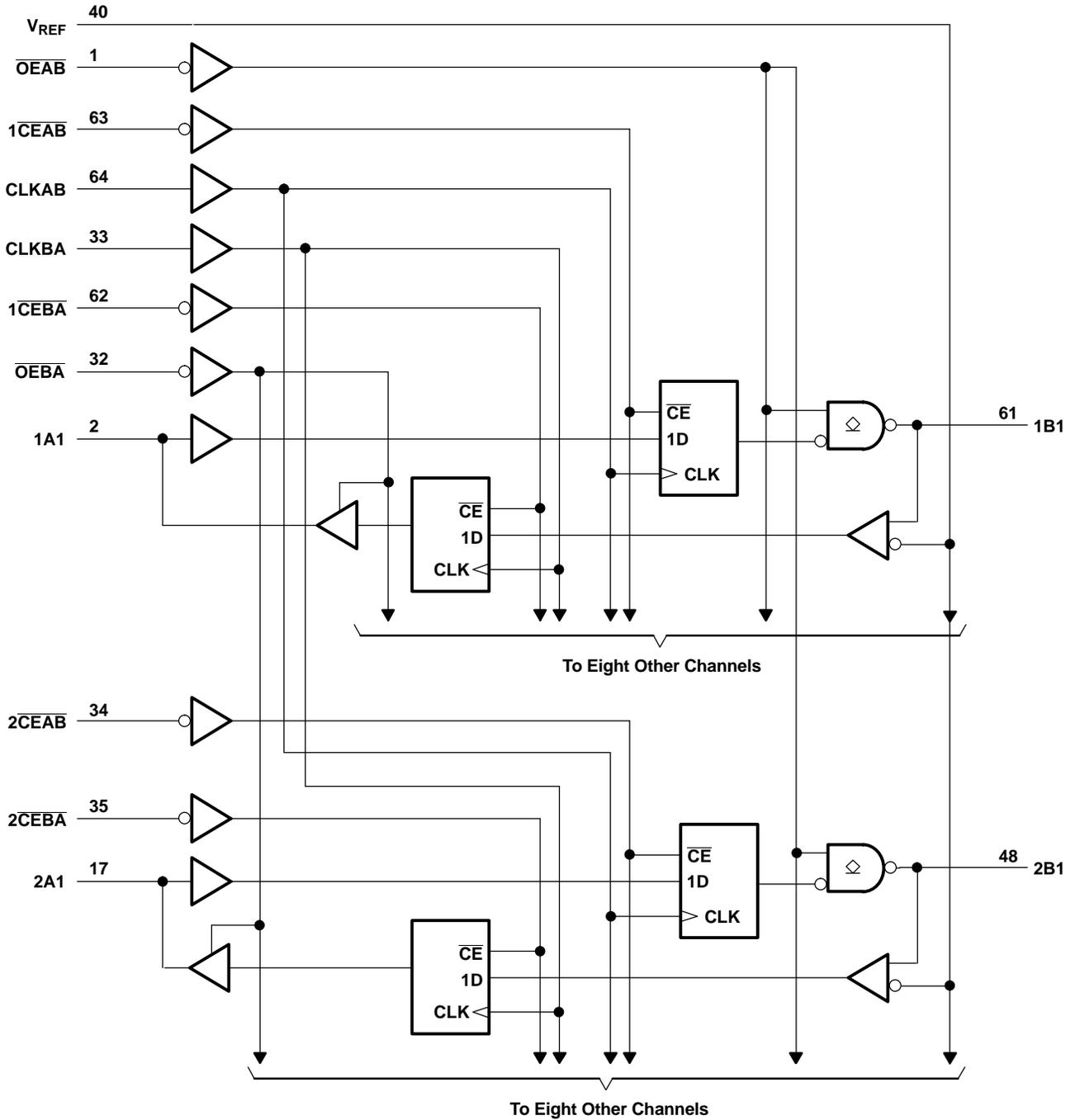
**FUNCTION TABLE<sup>(1)</sup>**

INPUTS				OUTPUT B	MODE
$\overline{CEAB}$	$\overline{OEAB}$	CLKAB	A		
X	H	X	X	Z	Isolation
H	L	X	X	$B_0^{(2)}$	Latched storage of A data
X	L	H or L	X	$B_0^{(2)}$	
L	L	↑	L	L	Clocked storage of A data
L	L	↑	H	H	

(1) A-to-B data flow is shown. B-to-A data flow is similar, but uses  $\overline{OEBA}$ , CLKBA, and  $\overline{CEBA}$ .

(2) Output level before the indicated steady-state input conditions are established

**LOGIC DIAGRAM (POSITIVE LOGIC)**



# SN74GTL16622A

## 18-BIT LVTTTL-TO-GTL/GTL+ BUS TRANSCEIVER

SCBS673F–AUGUST 1996–REVISED APRIL 2005

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	A-port and control inputs	-0.5	6.5	V
		B port and $V_{REF}$	-0.5	4.6	
$V_O$	Voltage range applied to any output in the high or power-off state <sup>(2)</sup>	A port	-0.5	6.5	V
		B port	-0.5	4.6	
$I_O$	Current into any output in the low state	A port		48	mA
		B port		100	
$I_O$	Current into any A-port output in the high state <sup>(3)</sup>			48	mA
	Continuous current through each $V_{CC}$ or GND			±100	mA
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>			55	°C/W
$T_{stg}$	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The current flows only when the output is in the high state and  $V_O > V_{CC}$ .
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)(2)(3)(4)</sup>

			MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage		3.15	3.3	3.45	V
$V_{TT}$	Termination voltage	GTL	1.14	1.2	1.26	V
		GTL+	1.35	1.5	1.65	
$V_{REF}$	Reference voltage	GTL	0.74	0.8	0.87	V
		GTL+	0.87	1	1.1	
$V_I$	Input voltage	B port			$V_{TT}$	V
		Except B port			5.5	
$V_{IH}$	High-level input voltage	B port	$V_{REF} + 50$ mV			V
		Except B port	2			
$V_{IL}$	Low-level input voltage	B port	$V_{REF} - 50$ mV			V
		Except B port	0.8			
$I_{IK}$	Input clamp current				-18	mA
$I_{OH}$	High-level output current	A port			-24	mA
$I_{OL}$	Low-level output current	A port			24	mA
		B port			50	
$T_A$	Operating free-air temperature		-40		85	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (2) Normal connection sequence is GND first and  $V_{CC} = 3.3$  V, I/O, control inputs,  $V_{TT}$  and  $V_{REF}$  (any order) last.
- (3)  $V_{TT}$  and  $R_{TT}$  can be adjusted to accommodate backplane impedances if the dc recommended  $I_{OL}$  ratings are not exceeded.
- (4)  $V_{REF}$  can be adjusted to optimize noise margins, but normally is two-thirds  $V_{TT}$ .

## Electrical Characteristics

over recommended operating free-air temperature range for GTL/GTL+ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP <sup>(1)</sup>	MAX	UNIT	
$V_{IK}$		$V_{CC} = 3.15\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2	V	
$V_{OH}$	A port	$V_{CC} = 3.15\text{ V to }3.45\text{ V}$ ,	$I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$			V	
		$V_{CC} = 3.15\text{ V}$	$I_{OH} = -12\text{ mA}$	2.4				
			$I_{OH} = -24\text{ mA}$	2				
$V_{OL}$	A port	$V_{CC} = 3.15\text{ V to }3.45\text{ V}$ ,	$I_{OL} = 100\text{ }\mu\text{A}$			0.2	V	
		$V_{CC} = 3.15\text{ V}$	$I_{OL} = 12\text{ mA}$			0.4		
			$I_{OL} = 24\text{ mA}$			0.5		
	B port	$V_{CC} = 3.15\text{ V to }3.45\text{ V}$ ,	$I_{OL} = 100\text{ }\mu\text{A}$					0.2
		$V_{CC} = 3.15\text{ V}$	$I_{OL} = 10\text{ mA}$					0.2
			$I_{OL} = 40\text{ mA}$					0.4
		$I_{OL} = 50\text{ mA}$				0.55		
$I_I$	B port	$V_{CC} = 3.45\text{ V}$ ,	$V_I = V_{TT}$ or GND			$\pm 5$	$\mu\text{A}$	
	A-port and control inputs	$V_{CC} = 3.45\text{ V}$	$V_I = V_{CC}$ or GND			$\pm 5$		
			$V_I = 5.5\text{ V}$ or GND			$\pm 20$		
$I_{off}$		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to $5.5\text{ V}$			100	$\mu\text{A}$	
$I_{I(hold)}$	A port	$V_{CC} = 3.15\text{ V}$	$V_I = 0.8\text{ V}$	75			$\mu\text{A}$	
			$V_I = 2\text{ V}$	-75				
		$V_{CC} = 3.45\text{ V}^{(2)}$ ,	$V_I = 0.8\text{ V to }2\text{ V}$			$\pm 500$		
$I_{OZ}^{(3)}$	A port	$V_{CC} = 3.45\text{ V}$ ,	$V_O = V_{CC}$ or GND			$\pm 10$	$\mu\text{A}$	
$I_{OZH}$	B port	$V_{CC} = 3.45\text{ V}$ ,	$V_O = 1.5\text{ V}$			10	$\mu\text{A}$	
$I_{CC}$	A or B port	$V_{CC} = 3.45\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs high			60	mA	
			Outputs low			60		
			Outputs disabled			60		
$\Delta I_{CC}^{(4)}$		$V_{CC} = 3.45\text{ V}$ , A-port or control inputs at $V_{CC}$ or GND, One input at $V_{CC} - 0.6\text{ V}$				500	$\mu\text{A}$	
$C_i$	Control inputs	$V_I = 3.15\text{ V}$ or 0			2.5	3	pF	
$C_{io}$	A port	$V_O = 3.15\text{ V}$ or 0			6	8	pF	
	B port				6.5	8.5		

(1) All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

**SN74GTL16622A**  
**18-BIT LVTTTL-TO-GTL/GTL+ BUS TRANSCEIVER**

SCBS673F–AUGUST 1996–REVISED APRIL 2005

**Timing Requirements**

over recommended ranges of supply voltage and operating free-air temperature for GTL (unless otherwise noted)

			MIN	MAX	UNIT
$f_{\text{clock}}$	Clock frequency			200	MHz
$t_w$	Pulse duration, CLK high or low		2.5		ns
$t_{\text{su}}$	Setup time	Data before CLK $\uparrow$	2.1		ns
		$\overline{\text{CE}}$ before CLK $\uparrow$	3.3		
$t_h$	Hold time	Data after CLK $\uparrow$	0.3		ns
		$\overline{\text{CE}}$ after CLK $\uparrow$	0		

**Switching Characteristics**

over recommended ranges of supply voltage and operating free-air temperature for GTL (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$f_{\text{max}}$			200			MHz
$t_{\text{PLH}}$	CLKAB	B	2.5		5.5	ns
$t_{\text{PHL}}$			2.2		5.5	
$t_{\text{dis}}$	$\overline{\text{OEAB}}$	B	1.7		4.8	ns
$t_{\text{en}}$			2.2		5.2	
Slew rate	Both transitions (B port)			0.5		V/ns
$t_r$	Transition time, B outputs (0.6 V to 1 V)		0.6		2.2	ns
$t_f$	Transition time, B outputs (1 V to 0.6 V)		0.4		1.5	ns
$t_{\text{PLH}}$	CLKBA	A	2.1		5.3	ns
$t_{\text{PHL}}$			2.1		5	
$t_{\text{en}}$	$\overline{\text{OEBA}}$	A	1.7		5	ns
$t_{\text{dis}}$			2.3		5.5	

(1) All typical values are at  $V_{\text{CC}} = 3.3 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

## Timing Requirements

over recommended ranges of supply voltage and operating free-air temperature for GTL+ (unless otherwise noted)

		MIN	MAX	UNIT
$f_{\text{clock}}$	Clock frequency		200	MHz
$t_w$	Pulse duration, CLK high or low	2.5		ns
$t_{\text{su}}$	Setup time	Data before CLK $\uparrow$	2.4	ns
		$\overline{\text{CE}}$ before CLK $\uparrow$	3.2	
$t_h$	Hold time	Data after CLK $\uparrow$	0.2	ns
		$\overline{\text{CE}}$ after CLK $\uparrow$	0	

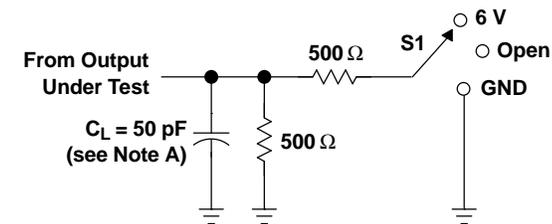
## Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature for GTL+ (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$f_{\text{max}}$			200			MHz
$t_{\text{PLH}}$	CLKAB	B	2.6	4	5.6	ns
$t_{\text{PHL}}$			2.3	4	5.7	
$t_{\text{PLH}}$	$\overline{\text{OEAB}}$	B	2.4	3.8	5.2	ns
$t_{\text{PHL}}$			1.8	3.4	5	
Slew rate	Both transitions (B port)		0.5			V/ns
$t_r$	Transition time, B outputs (0.6 V to 1.3 V)		1	1.6	2.7	ns
$t_f$	Transition time, B outputs (1.3 V to 0.6 V)		0.5	1.1	3.2	ns
$t_{\text{PLH}}$	CLKBA	A	2	3.8	5.3	ns
$t_{\text{PHL}}$			1.9	3.6	5	
$t_{\text{en}}$	$\overline{\text{OEBA}}$	A	1.9	3.6	5	ns
$t_{\text{dis}}$			2.1	4	5.5	

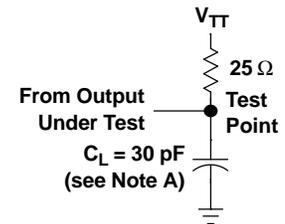
(1) All typical values are at  $V_{\text{CC}} = 3.3 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

PARAMETER MEASUREMENT INFORMATION

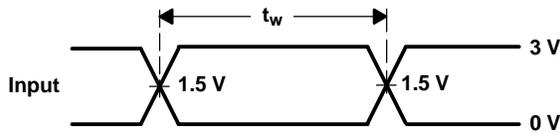


LOAD CIRCUIT FOR A OUTPUTS

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



LOAD CIRCUIT FOR B OUTPUTS



VOLTAGE WAVEFORMS  
PULSE DURATION

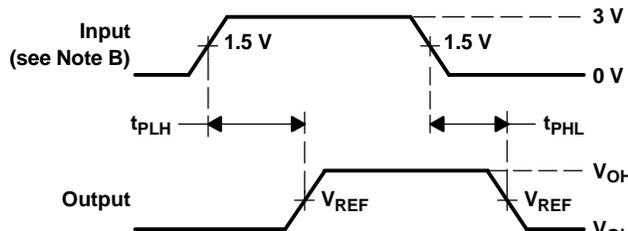


Timing  
Input

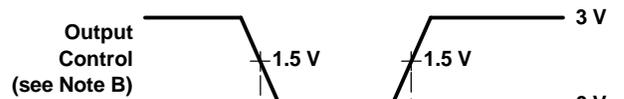
Data Input  
A Port

Data Input  
B Port

VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
(CLKAB to B port)

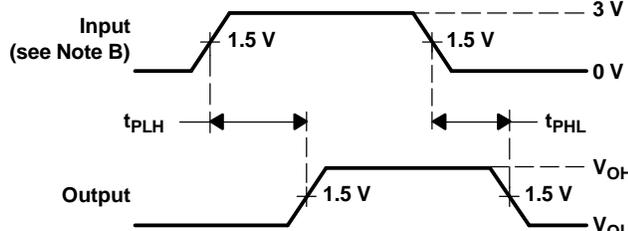


Output  
Control  
(see Note B)

Output  
Waveform 1  
S1 at 6 V  
(see Note C)

Output  
Waveform 2  
S1 at GND  
(see Note C)

VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
(OEBA to A port)



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
(CLKBA to A port)

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.  
C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.  
Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
74GTL16622ADGGRE4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74GTL16622ADGGRG4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74GTL16622ADGGR	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

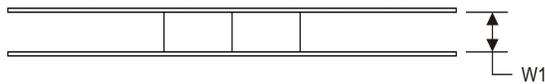
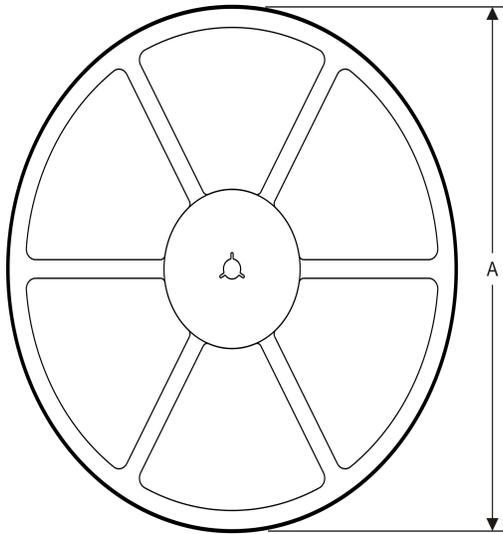
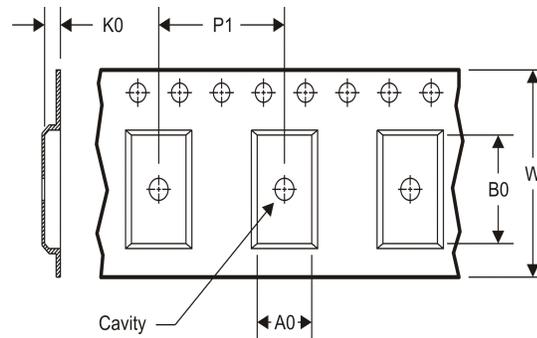
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


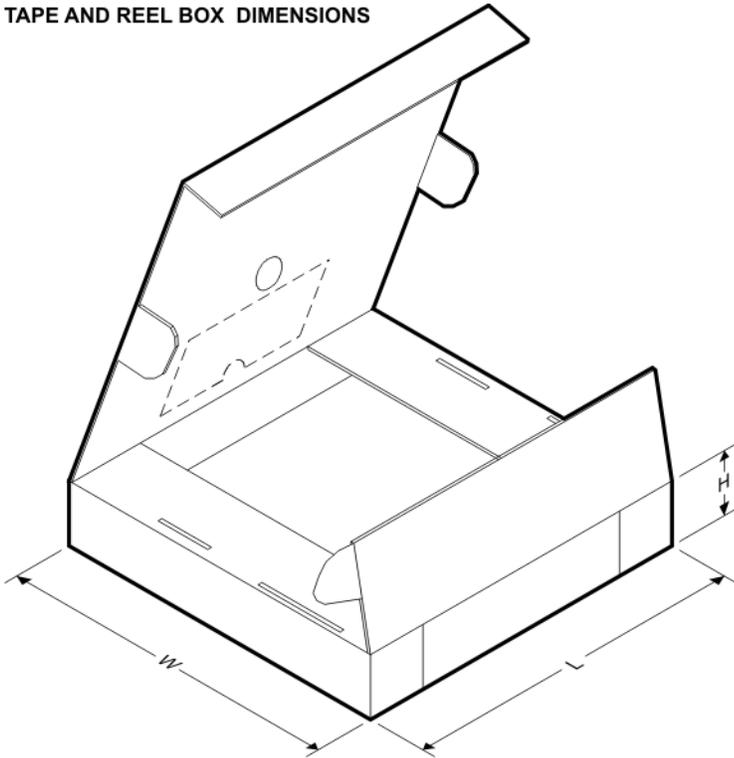
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74GTL16622ADGGR	TSSOP	DGG	64	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



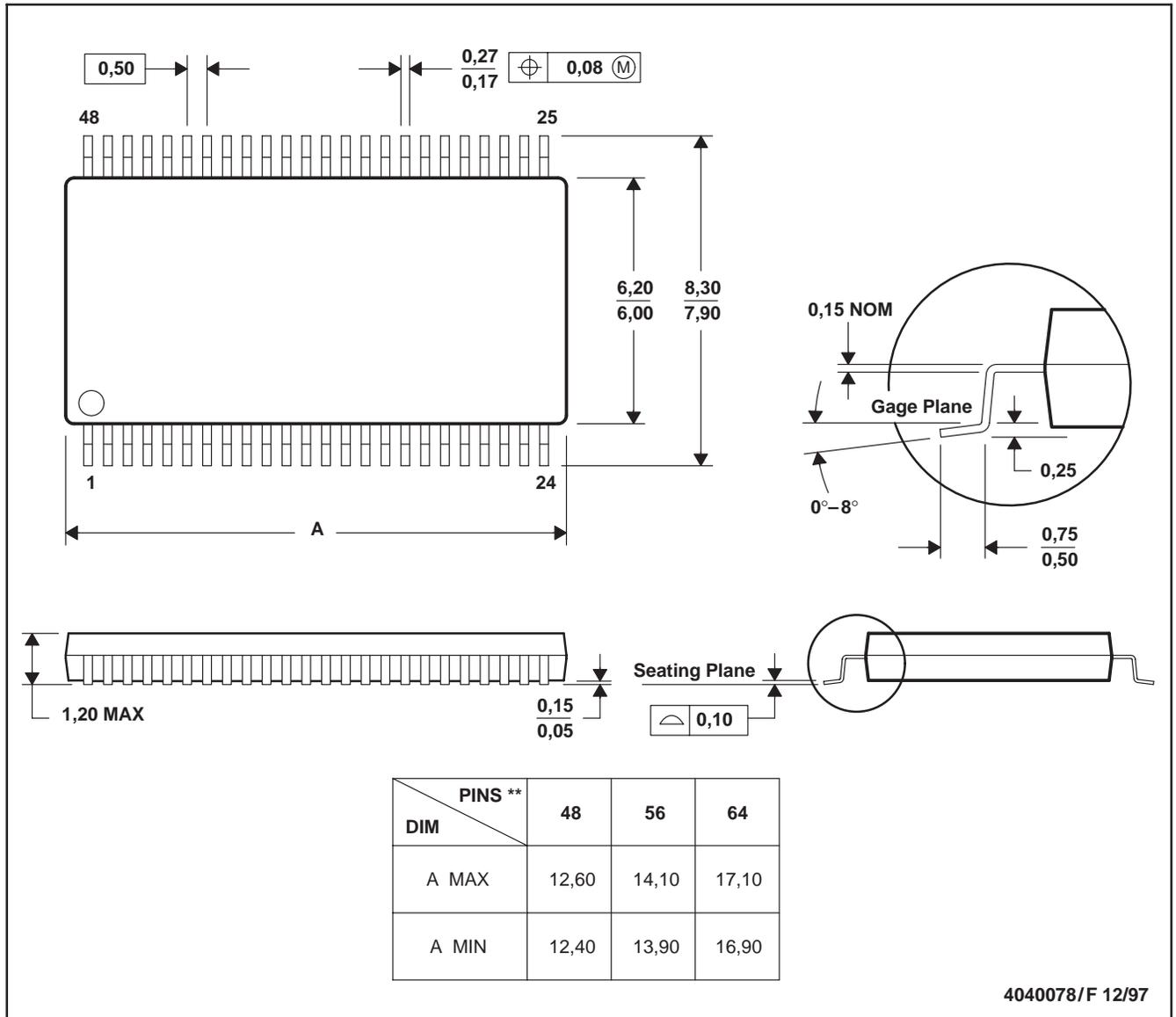
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74GTL16622ADGGR	TSSOP	DGG	64	2000	367.0	367.0	45.0

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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